

# SN74ACT7541-Q1 Automotive Octal Buffers or Drivers With Open-Drain Outputs

## 1 Features

- AEC-Q100 qualified for automotive applications:
  - Device temperature grade 1: -40°C to +125°C
  - Device HBM ESD classification level 2
  - Device CDM ESD classification level C4B
- Available in [wetttable flank](#) QFN package
- Operating voltage range of 4.5V to 5.5V
- TTL-compatible inputs
- Continuous 24mA output drive at 5V
- Supports up to 75mA output drive at 5V in short bursts
- Drives 50Ω transmission lines
- Fast operation with delay of 9.6ns max ( $V_{CC} = 5V$ ,  $C_L = 50pF$ )

## 2 Applications

- [Drive an indicator LED](#)
- [Level-shift using open-drain outputs](#)
- Control a relay

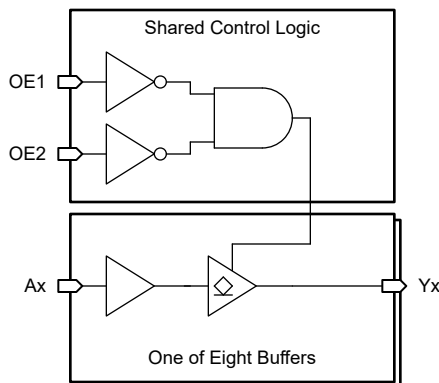
## 3 Description

The SN74ACT7541-Q1 contains eight independent buffers with open-drain outputs. All channels can be simultaneously forced into the high-impedance state using either of the output enable inputs ( $\overline{OE1}$  or  $\overline{OE2}$ ).

### Package Information

PART NUMBER	PACKAGE <sup>(1)</sup>	PACKAGE SIZE <sup>(2)</sup>	BODY SIZE <sup>(3)</sup>
SN74ACT7541-Q1	RKS (VQFN, 20)	4.5mm × 2.5mm	4.5mm × 2.5mm
	PW (TSSOP, 20)	6.5mm × 6.4mm	6.5mm × 4.4mm
	DGS (VSSOP, 20)	5.1mm × 4.9mm	5.1mm × 3mm

- (1) For more information, see [Section 11](#).
- (2) The package size (length × width) is a nominal value and includes pins, where applicable
- (3) The body size (length × width) is a nominal value and does not include pins.



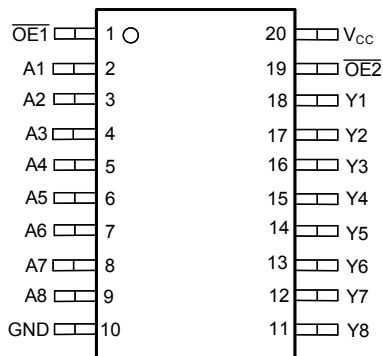
**Logic Diagram (Positive Logic)**



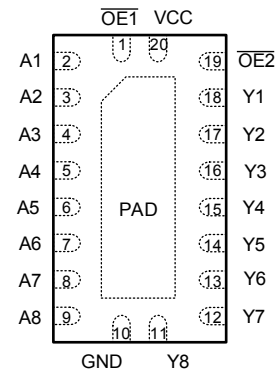
## Table of Contents

<b>1 Features</b> .....	1	<b>8 Application and Implementation</b> .....	11
<b>2 Applications</b> .....	1	8.1 Application Information.....	11
<b>3 Description</b> .....	1	8.2 Typical Application.....	11
<b>4 Pin Configuration and Functions</b> .....	3	8.3 Design Requirements.....	11
<b>5 Specifications</b> .....	4	8.4 Detailed Design Procedure.....	12
5.1 Absolute Maximum Ratings.....	4	8.5 Application Curves.....	13
5.2 ESD Ratings.....	4	8.6 Power Supply Recommendations.....	13
5.3 Recommended Operating Conditions.....	4	8.7 Layout.....	13
5.4 Thermal Information.....	4	<b>9 Device and Documentation Support</b> .....	15
5.5 Electrical Characteristics.....	5	9.1 Receiving Notification of Documentation Updates....	15
5.6 Switching Characteristics.....	5	9.2 Support Resources.....	15
5.7 Typical Characteristics.....	6	9.3 Trademarks.....	15
<b>6 Parameter Measurement Information</b> .....	7	9.4 Electrostatic Discharge Caution.....	15
<b>7 Detailed Description</b> .....	8	9.5 Glossary.....	15
7.1 Overview.....	8	<b>10 Revision History</b> .....	15
7.2 Functional Block Diagram.....	8	<b>11 Mechanical, Packaging, and Orderable Information</b> .....	15
7.3 Feature Description.....	8		
7.4 Device Functional Modes.....	10		

## 4 Pin Configuration and Functions



**Figure 4-1. PW and DGS Package,  
20-Pin TSSOP and VSSOP  
(Top View)**



**Figure 4-2. RKS Package,  
20-Pin VQFN  
(Top View)**

**Table 4-1. Pin Functions**

PIN		TYPE <sup>(1)</sup>	DESCRIPTION
NAME	NO.		
OE1	1	I	Output enable input 1, active low
A1	2	I	Input for channel 1
A2	3	I	Input for channel 2
A3	4	I	Input for channel 3
A4	5	I	Input for channel 4
A5	6	I	Input for channel 5
A6	7	I	Input for channel 6
A7	8	I	Input for channel 7
A8	9	I	Input for channel 8
GND	10	G	Ground
Y8	11	O	Output for channel 8
Y7	12	O	Output for channel 7
Y6	13	O	Output for channel 6
Y5	14	O	Output for channel 5
Y4	15	O	Output for channel 4
Y3	16	O	Output for channel 3
Y2	17	O	Output for channel 2
Y1	18	O	Output for channel 1
OE2	19	I	Output enable input 2, active low
V <sub>CC</sub>	20	P	Positive supply
Thermal Pad <sup>(2)</sup>		—	The thermal pad can be connect to GND or left floating. Do not connect to any other signal or supply.

(1) I = Input, O = Output, I/O = Input or Output, G = Ground, P = Power.

(2) RKS package only.

## 5 Specifications

### 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range		-0.5	7	V
V <sub>I</sub>	Input voltage range <sup>(2)</sup>		-0.5	V <sub>CC</sub> + 0.5V	V
V <sub>O</sub>	Output voltage range <sup>(2)</sup>		-0.5	V <sub>CC</sub> + 0.5V	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < -0.5V or V <sub>I</sub> > V <sub>CC</sub> + 0.5V		±20	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < -0.5V or V <sub>O</sub> > V <sub>CC</sub> + 0.5V		±50	mA
I <sub>O</sub>	Continuous output current	V <sub>O</sub> = 0 to V <sub>CC</sub>		±50	mA
	Continuous output current through V <sub>CC</sub> or GND			±200	mA
T <sub>J</sub>	Junction temperature			150	°C
T <sub>stg</sub>	Storage temperature		-65	150	°C

- Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. Absolute maximum ratings do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If briefly operating outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not sustain damage, but it may not be fully functional. Operating the device in this manner may affect device reliability, functionality, performance, and shorten the device lifetime.
- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 5.2 ESD Ratings

			VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per AEC Q100-002 HBM ESD Classification Level 2 <sup>(1)</sup>	±2000	V
		Charged device model (CDM), per AEC Q100-011 CDM ESD Classification Level C4B	±1000	

- AEC Q100-002 indicate that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

### 5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

Specification	Description	Condition	MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		4.5	5.5	V
V <sub>IH</sub>	High-level input voltage	4.5V ≤ V <sub>CC</sub> ≤ 5.5V	2		V
V <sub>IL</sub>	Low-Level input voltage	4.5V ≤ V <sub>CC</sub> ≤ 5.5V		0.8	V
V <sub>I</sub> <sup>(1)</sup>	Input Voltage		0	V <sub>CC</sub>	V
V <sub>O</sub>	Output Voltage		0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	4.5V ≤ V <sub>CC</sub> ≤ 5.5V		-24	mA
I <sub>OL</sub>	Low-level output current	4.5V ≤ V <sub>CC</sub> ≤ 5.5V		24	mA
Δt/Δv	Input transition rise or fall rate	4.5V ≤ V <sub>CC</sub> ≤ 5.5V		20	ns/V
T <sub>A</sub>	Operating free-air temperature		-40	125	°C

- All unused inputs of the device must be held at a valid high or low voltage level for proper device operation. Refer to the TI application report [Implications of Slow or Floating CMOS Inputs](#).

### 5.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		DGS (VSSOP)	PW (TSSOP)	RKS (VQFN)	UNIT
		20 PINS	20 PINS	20 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	123.5	126.2	67.7	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	62.1	68.7	72.4	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	78.5	77.3	40.4	°C/W

THERMAL METRIC <sup>(1)</sup>		DGS (VSSOP)	PW (TSSOP)	RKS (VQFN)	UNIT
		20 PINS	20 PINS	20 PINS	
$\Psi_{JT}$	Junction-to-top characterization parameter	7.8	22.3	10.3	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	78	76.9	40.4	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	24.1	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 5.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$V_{CC}$	$T_A = 25^\circ\text{C}$			$-40^\circ\text{C to } 125^\circ\text{C}$			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
$V_{OH}$	$I_{OH} = -50\mu\text{A}$	4.5V	4.4	4.49		4.4		V	
		5.5V	5.4	5.49		5.4			
	$I_{OH} = -24\text{mA}$	4.5V	3.94			3.7			
		5.5V	4.86			4.7			
	$I_{OH} = -50\text{mA}$	5.5V				3.85			
$I_{OH} = -75\text{mA}$	5.5V				3.85				
$V_{OL}$	$I_{OH} = 50\mu\text{A}$	4.5V		0.001	0.1		0.1	V	
		5.5V		0.001	0.1		0.1		
	$I_{OH} = 24\text{mA}$	4.5V			0.36		0.5		
		5.5V			0.36		0.5		
	$I_{OH} = 50\text{mA}$	5.5V					1.65		
$I_{OH} = 75\text{mA}$	5.5V					1.65			
$I_I$	$V_I = 5.5\text{V or GND}$	0V to 5.5V			$\pm 0.1$		$\pm 1$	$\mu\text{A}$	
$I_{OZ}$	$V_O = V_{CC} \text{ or GND}$	5.5V			$\pm 0.25$		$\pm 5$	$\mu\text{A}$	
$I_{CC}$	$V_I = V_{CC} \text{ or GND, } I_O = 0$	5.5V			2		80	$\mu\text{A}$	
$\Delta I_{CC}$	$V_I = V_{CC} - 2.1\text{V; Any Input}$	4.5V to 5.5V		0.6	1.2		1.5	mA	
$C_I$	$V_I = V_{CC} \text{ or GND}$	5V		8				pF	
$C_O$	$V_O = V_{CC} \text{ or GND}$	5V		14				pF	
$C_{PD}$	$C_L = 50\text{pF, } F = 1\text{MHz}$	5V		19				pF	

## 5.6 Switching Characteristics

$C_L = 50 \text{ pF}$ ; over operating free-air temperature range; typical values measured at  $T_A = 25^\circ\text{C}$  (unless otherwise noted).

See *Parameter Measurement Information*

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			$-40^\circ\text{C to } 125^\circ\text{C}$			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
$t_{PLH}$	A	Y	5V		4.2	5.8		7.1	ns	
$t_{PHL}$	A	Y	5V		5	8.1		9.6	ns	
$t_{PZH}$	OE	Y	5V		6.3	9.5		11.5	ns	
$t_{PZL}$	OE	Y	5V		6.5	10		11.9	ns	
$t_{PHZ}$	OE	Y	5V		5.3	6.8		7.8	ns	
$t_{PLZ}$	OE	Y	5V		3.8	5.2		6.3	ns	

## 5.7 Typical Characteristics

T<sub>A</sub> = 25°C (unless otherwise noted)

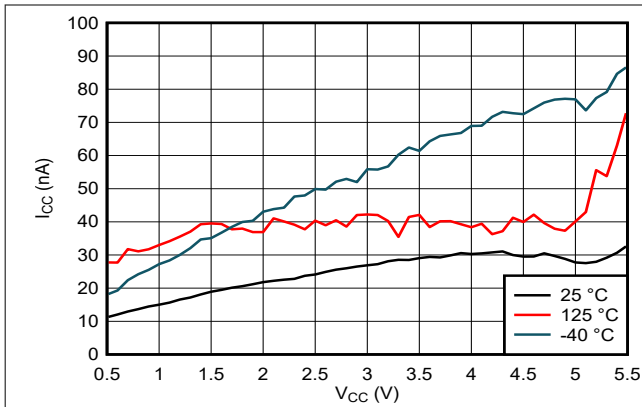


Figure 5-1. Supply Current Across Supply Voltage

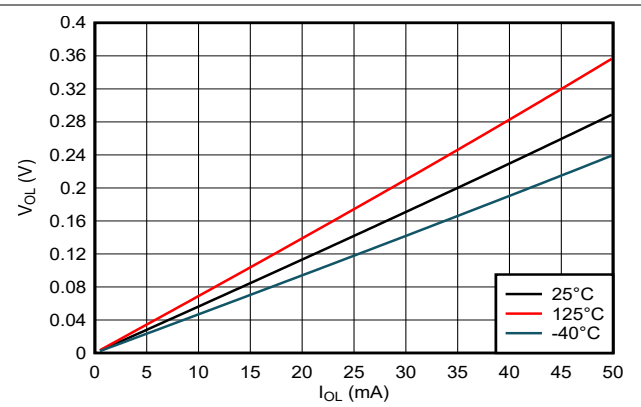


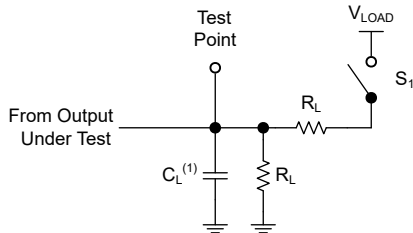
Figure 5-2. Output Voltage vs Current in LOW State; 5-V Supply

## 6 Parameter Measurement Information

Phase relationships between waveforms were chosen arbitrarily for the examples listed in the following table. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1MHz, Z<sub>O</sub> = 50Ω, t<sub>t</sub> < 2.5ns, V<sub>t</sub> = 1.5V.

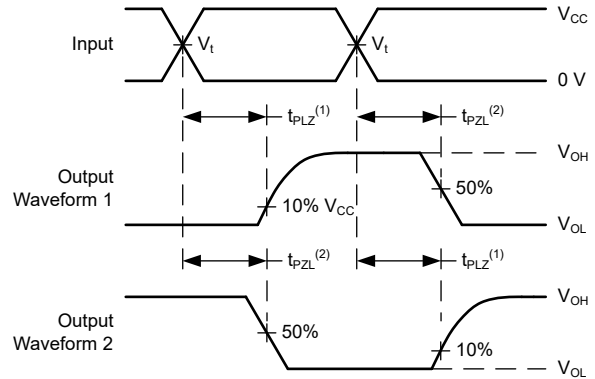
The outputs are measured individually with one input transition per measurement.

TEST	S1	R <sub>L</sub>	C <sub>L</sub>	ΔV	V <sub>LOAD</sub>
t <sub>PLZ</sub> , t <sub>PZL</sub>	CLOSED	500Ω	50pF	0.3V	2×V <sub>CC</sub>



(1) C<sub>L</sub> includes probe and test-fixture capacitance.

**Figure 6-1. Load Circuit for Open-Drain Outputs**



(1) t<sub>PLZ</sub> is the same as t<sub>dis</sub>.

(2) t<sub>PZL</sub> is the same as t<sub>en</sub>.

**Figure 6-2. Voltage Waveforms Propagation Delays**

## 7 Detailed Description

### 7.1 Overview

The SN74ACT7541-Q1 contains eight buffers with open-drain outputs. The active low output enable pins ( $\overline{OE1}$  and  $\overline{OE2}$ ) control all eight channels, and are configured so that both must be low for the outputs to be active.

When the outputs are enabled, the outputs are actively driven low or set into the high-impedance state.

When the outputs are disabled, the outputs are set into the high-impedance state.

### 7.2 Functional Block Diagram

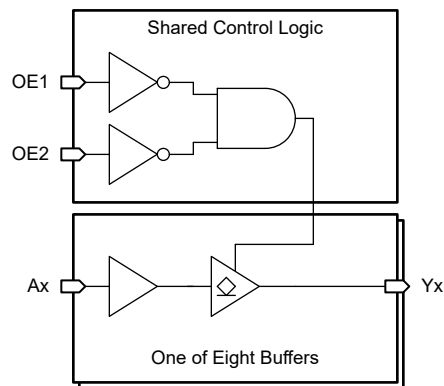


Figure 7-1. Logic Diagram (Positive Logic)

### 7.3 Feature Description

#### 7.3.1 Open-Drain CMOS Outputs

This device includes open-drain CMOS outputs. Open-drain outputs can only drive the output low. When in the high logical state, open-drain outputs will be in a high-impedance state. The drive capability of this device may create fast edges into light loads, so routing and load conditions should be considered to prevent ringing. Additionally, the outputs of this device are capable of driving larger currents than the device can sustain without being damaged. It is important for the output power of the device to be limited to avoid damage due to overcurrent. The electrical and thermal limits defined in the *Absolute Maximum Ratings* must be followed at all times.

When placed into the high-impedance state, the output will neither source nor sink current, with the exception of minor leakage current as defined in the *Electrical Characteristics* table. In the high-impedance state, the output voltage is not controlled by the device and is dependent on external factors. If no other drivers are connected to the node, then this is known as a floating node and the voltage is unknown. A pull-up resistor can be connected to the output to provide a known voltage at the output while it is in the high-impedance state. The value of the resistor will depend on multiple factors, including parasitic capacitance and power consumption limitations. Typically, a 10kΩ resistor can be used to meet these requirements.

Unused open-drain CMOS outputs should be left disconnected.

#### 7.3.2 TTL-Compatible CMOS Inputs

This device includes TTL-compatible CMOS inputs. These inputs are specifically designed to interface with TTL logic devices by having a reduced input voltage threshold.

TTL-compatible CMOS inputs are high impedance and are typically modeled as a resistor in parallel with the input capacitance given in the *Electrical Characteristics*. The worst case resistance is calculated with the maximum input voltage, given in the *Absolute Maximum Ratings*, and the maximum input leakage current, given in the *Electrical Characteristics*, using Ohm's law ( $R = V \div I$ ).

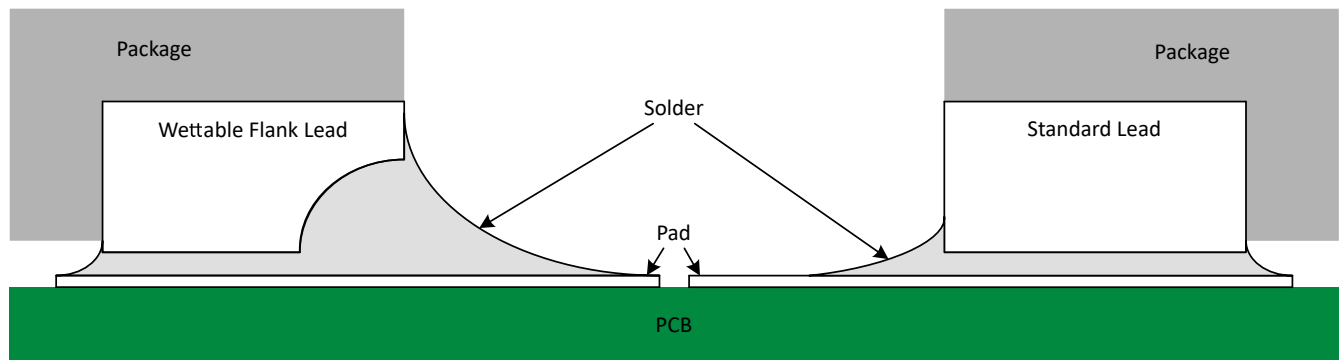


TTL-compatible CMOS inputs require that input signals transition between valid logic states quickly, as defined by the input transition time or rate in the *Recommended Operating Conditions* table. Failing to meet this specification will result in excessive power consumption and could cause oscillations. More details can be found in the *Implications of Slow or Floating CMOS Inputs* application report.

Do not leave TTL-compatible CMOS inputs floating at any time during operation. Unused inputs must be terminated at  $V_{CC}$  or GND. If a system will not be actively driving an input at all times, a pull-up or pull-down resistor can be added to provide a valid input voltage during these times. The resistor value will depend on multiple factors; however, a 10k $\Omega$  resistor is recommended and typically will meet all requirements.

### 7.3.3 Wettable Flanks

This device includes wettable flanks for at least one package. See the *Features* section on the front page of the data sheet where packages include this feature.



**Figure 7-2. Simplified Cutaway View of Wettable-Flank QFN Package and Standard QFN Package After Soldering**

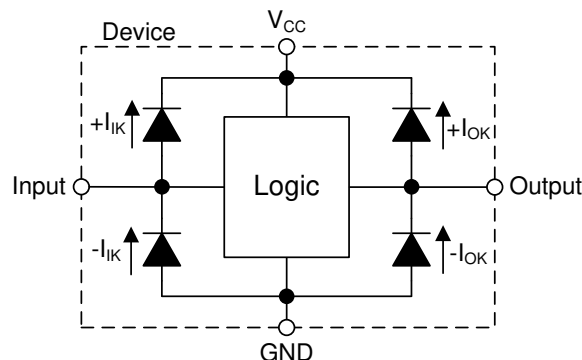
Wettable flanks help improve side wetting after soldering, which makes QFN packages easier to inspect with automatic optical inspection (AOI). As shown in [Figure 7-2](#), a wettable flank can be dimpled or step-cut to provide additional surface area for solder adhesion which assists in reliably creating a side fillet. See the mechanical drawing for additional details.

### 7.3.4 Clamp Diode Structure

As shown in [Figure 7-3](#), the inputs and outputs to this device have both positive and negative clamping diodes.

**CAUTION**

Voltages beyond the values specified in the *Absolute Maximum Ratings* table can cause damage to the device. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



**Figure 7-3. Electrical Placement of Clamping Diodes for Each Input and Output**

## 7.4 Device Functional Modes

**Table 7-1. Function Table**

INPUTS <sup>(1)</sup>			OUTPUT <sup>(2)</sup>
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	L
L	L	H	Z
H	X	X	Z
X	H	X	Z

- (1) L = input low, H = input high, X = do not care  
(2) L = output low, Z = high impedance

## 8 Application and Implementation

### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

### 8.1 Application Information

Open-drain outputs like those available in the SN74ACT7541-Q1 provide the ability to discharge a voltage node to ground without otherwise loading the node significantly. It is recommended to add a series resistor between the output and any capacitance larger than 50pF as shown in the *Typical Application Block Diagram* to prevent damage to the device.

The required resistor value can be determined using the maximum capacitor voltage and the maximum continuous current for the output from the equation:  $R \geq V_C / I_{O(max)}$ .

For any given RC combination, the discharge time can be determined using the discharge plot provided in the *Application Timing Diagram* and the equation  $\tau = R \times C$ . For example, to discharge a capacitor to 10% of the starting value, it takes approximately  $2.303 \times \tau = 2.303 \times R \times C$  seconds.

### 8.2 Typical Application

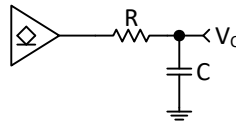


Figure 8-1. Typical Application Block Diagram

### 8.3 Design Requirements

#### 8.3.1 Power Considerations

Ensure the desired supply voltage is within the range specified in the *Recommended Operating Conditions*. The supply voltage sets the device's electrical characteristics of the device as described in the *Electrical Characteristics* section.

The positive voltage supply must be capable of sourcing current equal to the maximum static supply current,  $I_{CC}$ , listed in the *Electrical Characteristics*, and any transient current required for switching.

The ground must be capable of sinking current equal to the total current to be sunk by all outputs of the SN74ACT7541-Q1 plus the maximum supply current,  $I_{CC}$ , listed in the *Electrical Characteristics*, and any transient current required for switching. The logic device can only sink as much current that can be sunk into its ground connection. Ensure the maximum total current through GND listed in the *Absolute Maximum Ratings* is not exceeded.

The SN74ACT7541-Q1 can drive a load with a total capacitance less than or equal to 50pF while still meeting all of the data sheet specifications. Larger capacitive loads can be applied; however, it is not recommended to exceed 50pF.

The SN74ACT7541-Q1 can drive a load with total resistance described by  $R_L \geq V_O / I_O$ , with the output voltage and current defined in the *Electrical Characteristics* table with  $V_{OL}$ . When outputting in the HIGH state, the output voltage in the equation is defined as the difference between the measured output voltage and the supply voltage at the  $V_{CC}$  pin.

Total power consumption can be calculated using the information provided in [CMOS Power Consumption and Cpd Calculation](#).

Thermal increase can be calculated using the information provided in [Thermal Characteristics of Standard Linear and Logic \(SLL\) Packages and Devices](#).

#### CAUTION

The maximum junction temperature,  $T_{J(max)}$  listed in the *Absolute Maximum Ratings*, is an additional limitation to prevent damage to the device. Do not violate any values listed in the *Absolute Maximum Ratings*. These limits are provided to prevent damage to the device.

### 8.3.2 Input Considerations

Input signals must cross  $V_{IL(max)}$  to be considered a logic LOW, and  $V_{IH(min)}$  to be considered a logic HIGH. Do not exceed the maximum input voltage range found in the *Absolute Maximum Ratings*.

Unused inputs must be terminated to either  $V_{CC}$  or ground. The unused inputs can be directly terminated if the input is completely unused, or they can be connected with a pull-up or pull-down resistor if the input will be used sometimes, but not always. A pull-up resistor is used for a default state of HIGH, and a pull-down resistor is used for a default state of LOW. The drive current of the controller, leakage current into the SN74ACT7541-Q1 (as specified in the *Electrical Characteristics*), and the desired input transition rate limits the resistor size. A 10k $\Omega$  resistor value is often used due to these factors.

The SN74ACT7541-Q1 has CMOS inputs and thus requires fast input transitions to operate correctly, as defined in the *Recommended Operating Conditions* table. Slow input transitions can cause oscillations, additional power consumption, and reduction in device reliability.

Refer to the *Feature Description* section for additional information regarding the inputs for this device.

### 8.3.3 Output Considerations

The ground voltage is used to produce the output LOW voltage. Sinking current into the output will increase the output voltage as specified by the  $V_{OL}$  specification in the *Electrical Characteristics*.

Open-drain outputs can be connected together directly to produce a wired-AND configuration or for additional output drive strength.

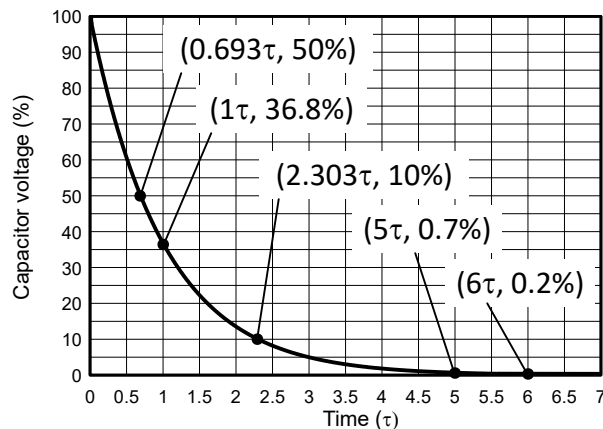
Unused outputs can be left floating. Do not connect outputs directly to  $V_{CC}$  or ground.

Refer to the *Feature Description* section for additional information regarding the outputs for this device.

## 8.4 Detailed Design Procedure

1. Add a decoupling capacitor from  $V_{CC}$  to GND. The capacitor needs to be placed physically close to the device and electrically close to both the  $V_{CC}$  and GND pins. An example layout is shown in the *Layout* section.
2. Ensure the capacitive load at the output is  $\leq 50$ pF. This is not a hard limit; by design, however, it will optimize performance. This can be accomplished by providing short, appropriately sized traces from the SN74ACT7541-Q1 to one or more of the receiving devices.
3. Ensure the resistive load at the output is larger than  $(V_{CC} / I_{O(max)})\Omega$ . Doing this will prevent the maximum output current from the *Absolute Maximum Ratings* from being violated. Most CMOS inputs have a resistive load measured in M $\Omega$ ; much larger than the minimum calculated previously.
4. Thermal issues are rarely a concern for logic gates; the power consumption and thermal increase, however, can be calculated using the steps provided in the application report, [CMOS Power Consumption and Cpd Calculation](#).

## 8.5 Application Curves



**Figure 8-2. Application Timing Diagram**

## 8.6 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each  $V_{CC}$  terminal should have a good bypass capacitor to prevent power disturbance. A  $0.1\mu\text{F}$  capacitor is recommended for this device. It is acceptable to parallel multiple bypass capacitors to reject different frequencies of noise. The  $0.1\mu\text{F}$  and  $1\mu\text{F}$  capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

## 8.7 Layout

### 8.7.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices, inputs must never be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or  $V_{CC}$ , whichever makes more sense for the logic function or is more convenient.

### 8.7.2 Layout Example

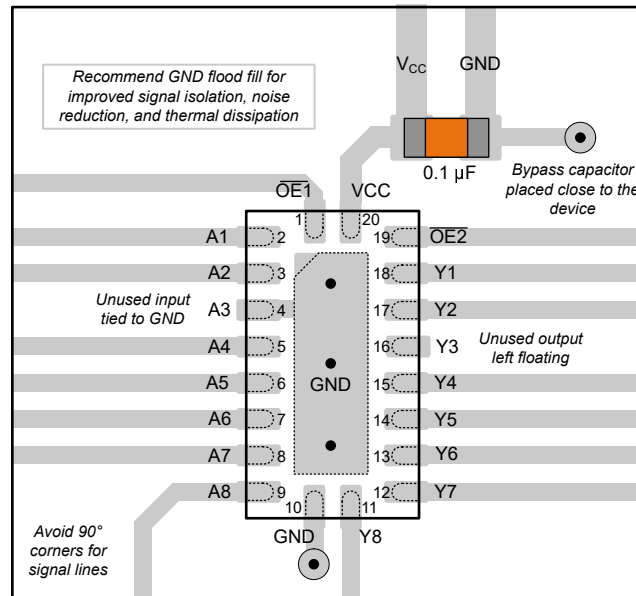


Figure 8-3. Example Layout for the SN74ACT7541-Q1 in the RKS Package

## 9 Device and Documentation Support

### 9.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 9.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 9.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.  
All trademarks are the property of their respective owners.

### 9.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 9.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 10 Revision History

DATE	REVISION	NOTES
March 2024	*	Initial Release

## 11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74ACT7541QWRKSRQ1	ACTIVE	VQFN	RKS	20	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CT7541Q	<a href="#">Samples</a>
SN74ACT7541QDGSRQ1	ACTIVE	VSSOP	DGS	20	5000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	O541Q	<a href="#">Samples</a>
SN74ACT7541QPWRQ1	ACTIVE	TSSOP	PW	20	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	ACT7541Q	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN74ACT7541-Q1 :**

- Catalog : [SN74ACT7541](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT7541QWRKSRQ1	VQFN	RKS	20	3000	180.0	12.4	2.8	4.8	1.2	4.0	12.0	Q1
SN74ACT7541QDGSRQ1	VSSOP	DGS	20	5000	330.0	16.4	5.4	5.4	1.45	8.0	16.0	Q1
SN74ACT7541QPWRQ1	TSSOP	PW	20	3000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ACT7541QWRKSRQ1	VQFN	RKS	20	3000	210.0	185.0	35.0
SN74ACT7541QDGSRQ1	VSSOP	DGS	20	5000	353.0	353.0	32.0
SN74ACT7541QPWRQ1	TSSOP	PW	20	3000	353.0	353.0	32.0

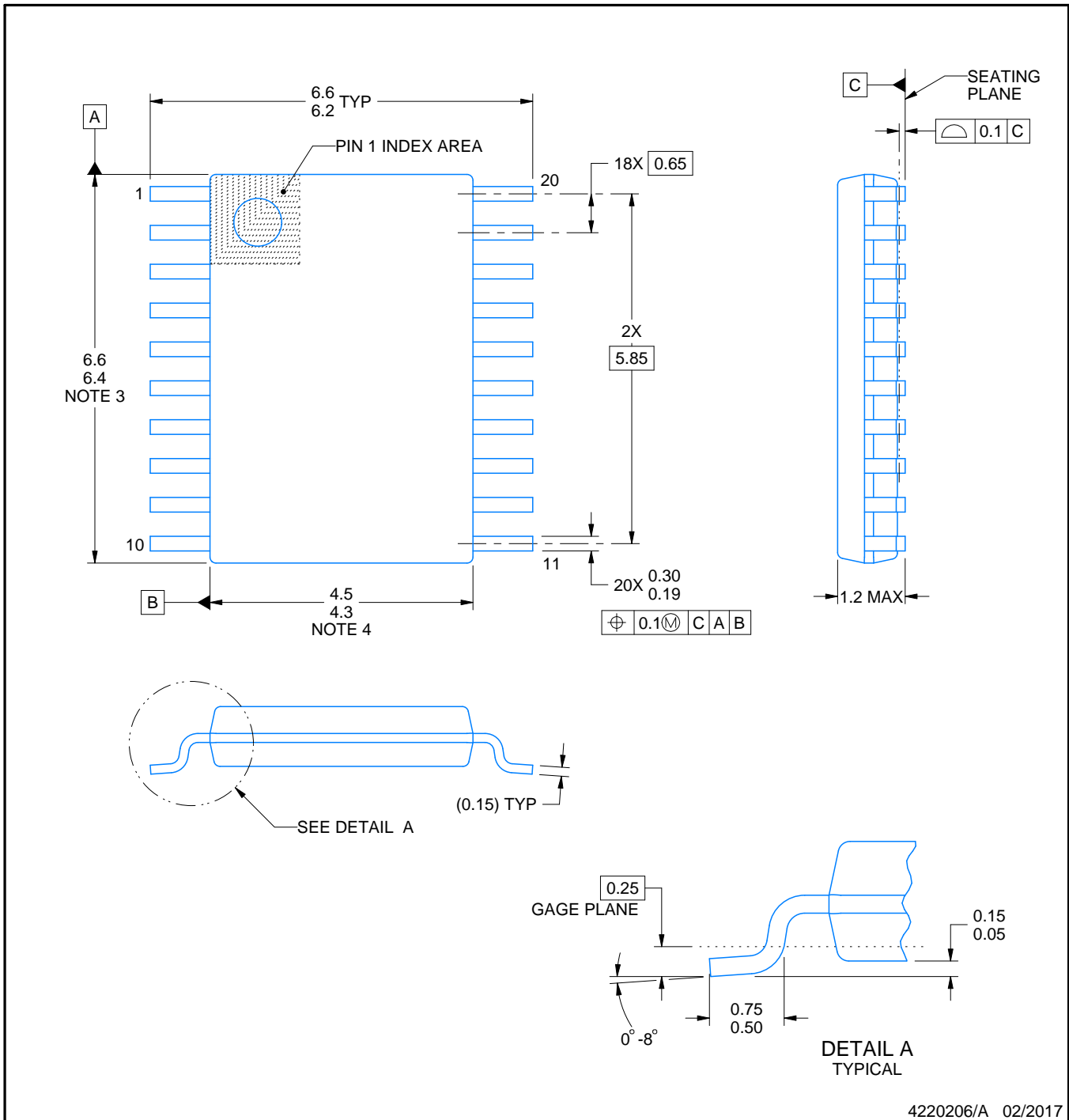
PW0020A



# PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220206/A 02/2017

## NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

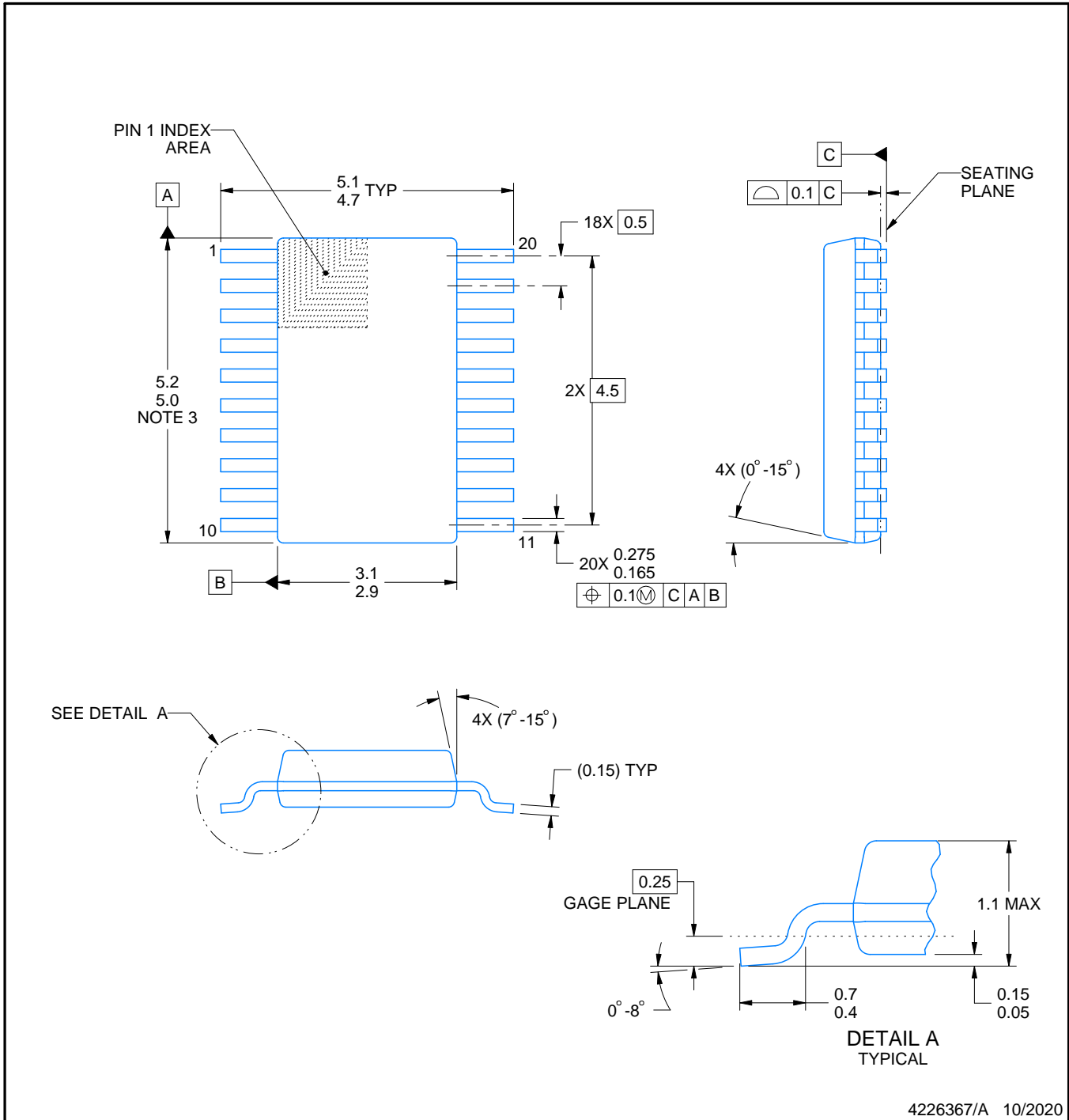
# DGS0020A



# PACKAGE OUTLINE

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



**NOTES:**

PowerPAD is a trademark of Texas Instruments.

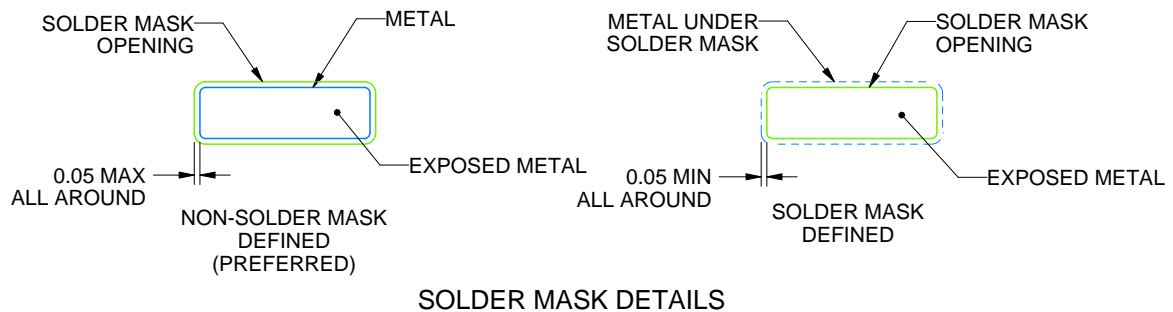
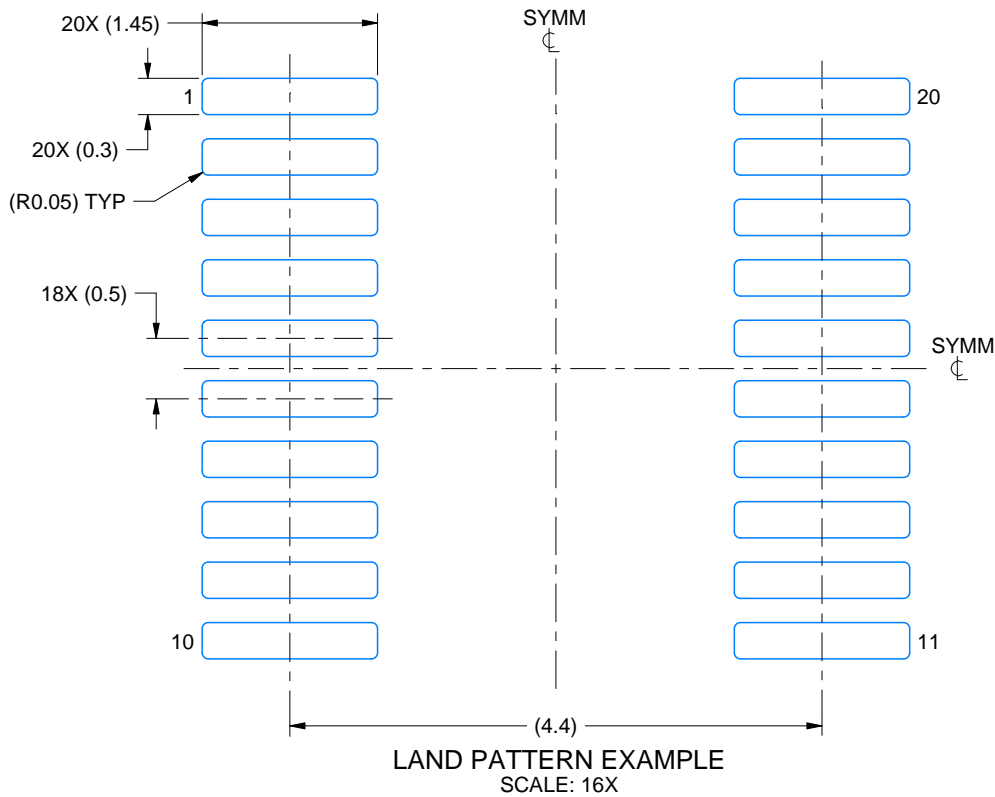
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. No JEDEC registration as of September 2020.
5. Features may differ or may not be present.

# EXAMPLE BOARD LAYOUT

DGS0020A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



4226367/A 10/2020

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 ([www.ti.com/lit/slma002](http://www.ti.com/lit/slma002)) and SLMA004 ([www.ti.com/lit/slma004](http://www.ti.com/lit/slma004)).
9. Size of metal pad may vary due to creepage requirement.
10. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.

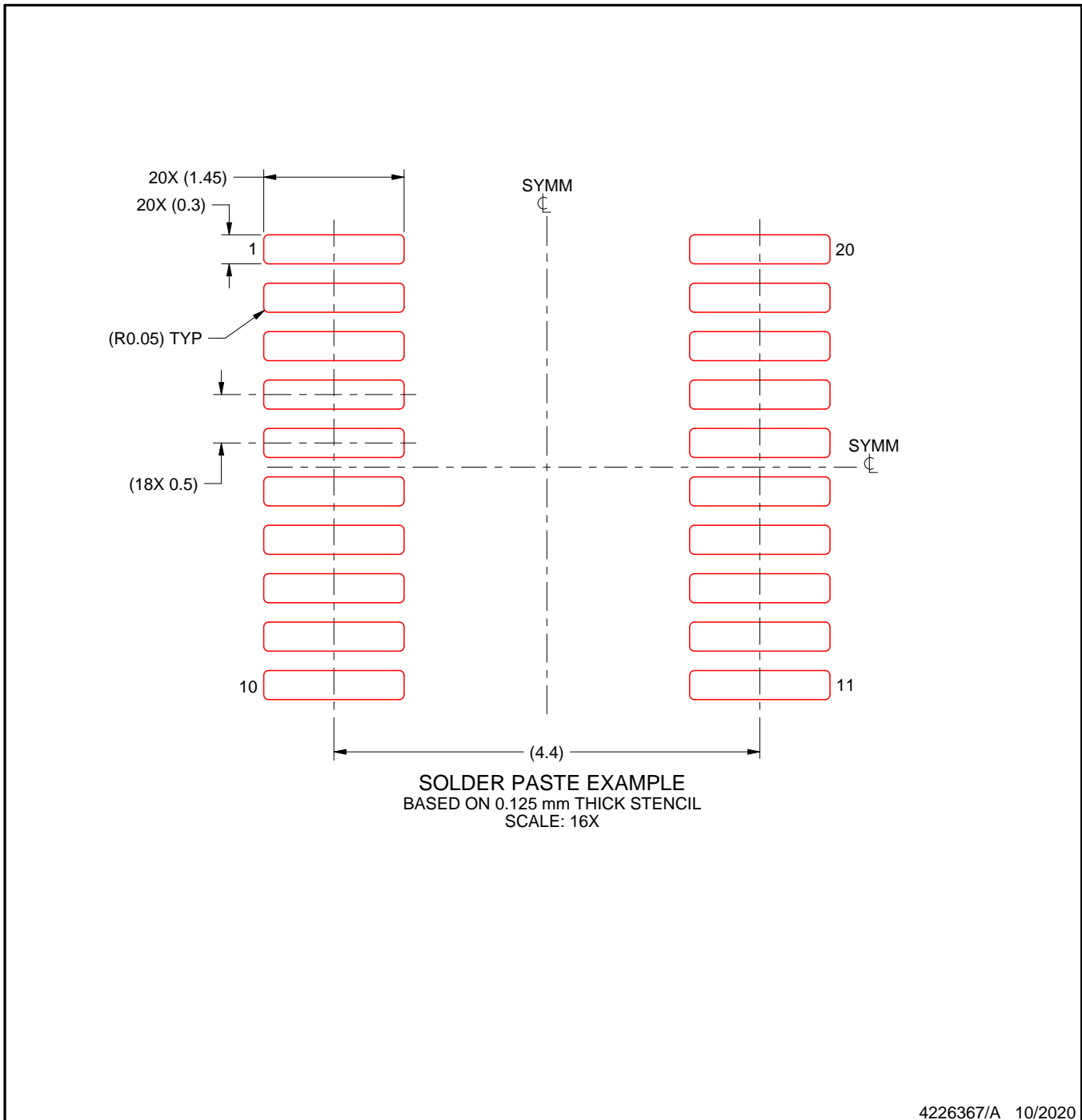


# EXAMPLE STENCIL DESIGN

DGS0020A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

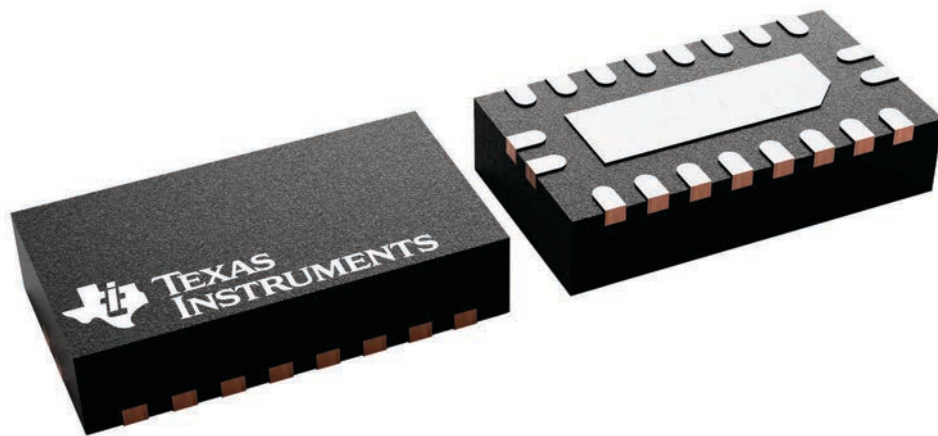
**RKS 20**

**VQFN - 1 mm max height**

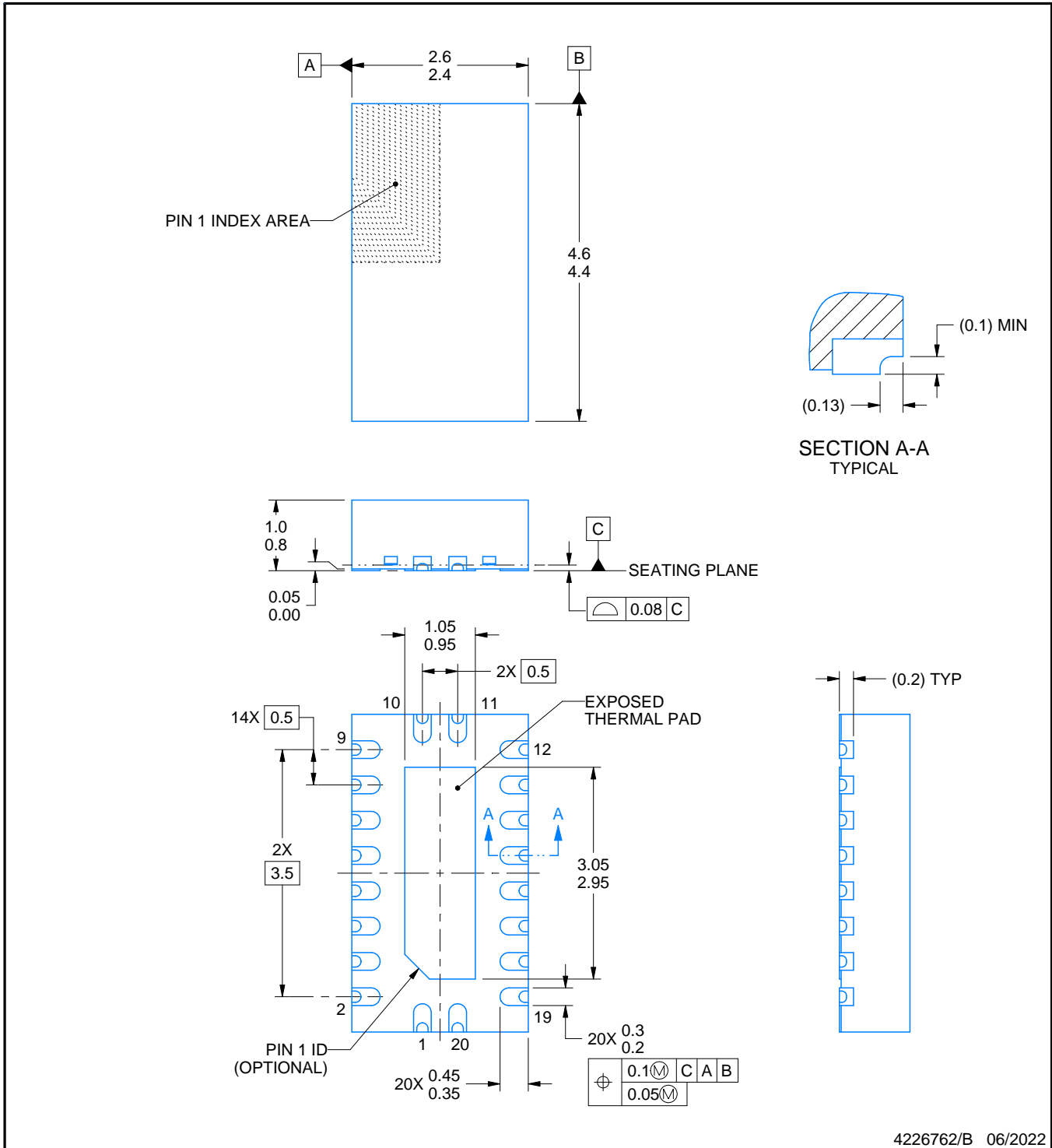
2.5 x 4.5, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4226872/A



4226762/B 06/2022

NOTES:

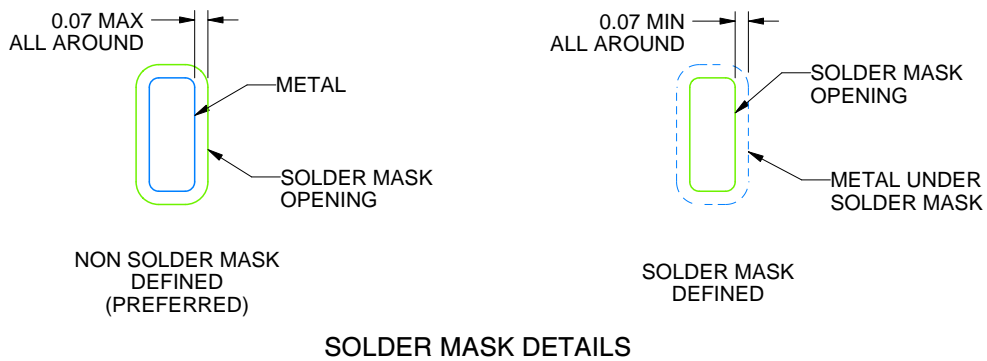
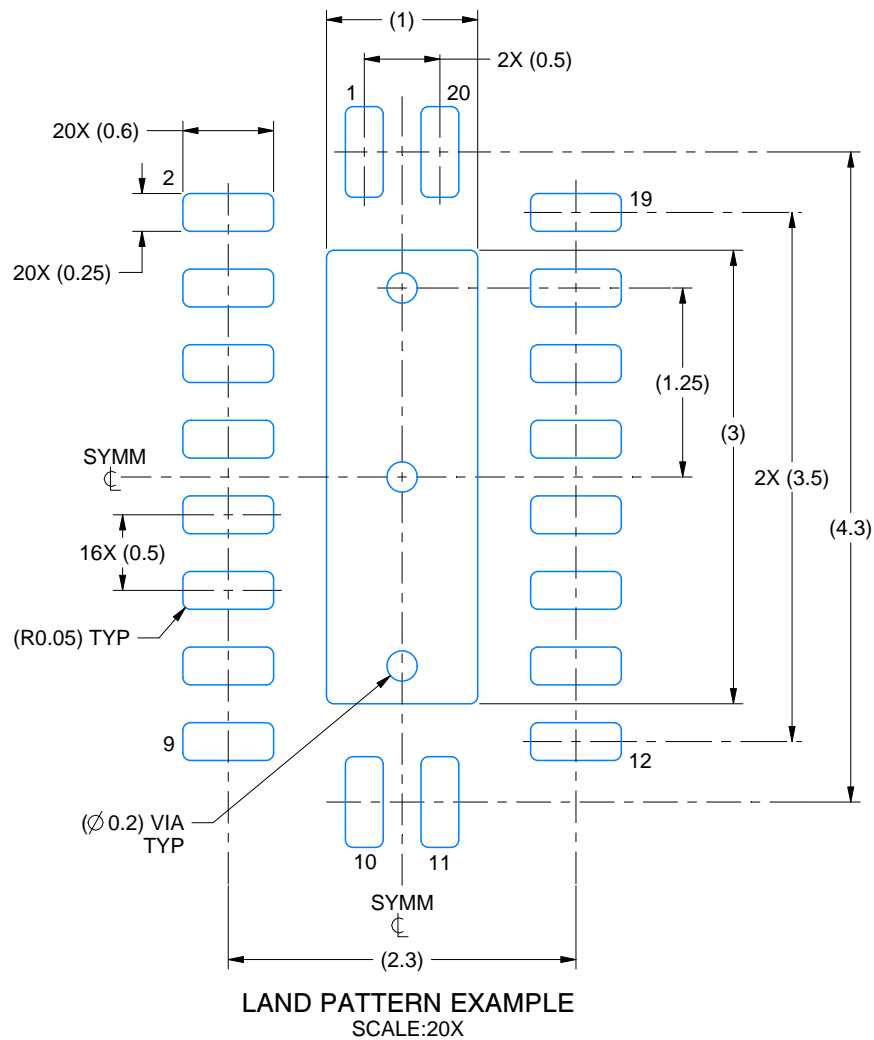
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

RKS0020B

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



4226762/B 06/2022

NOTES: (continued)

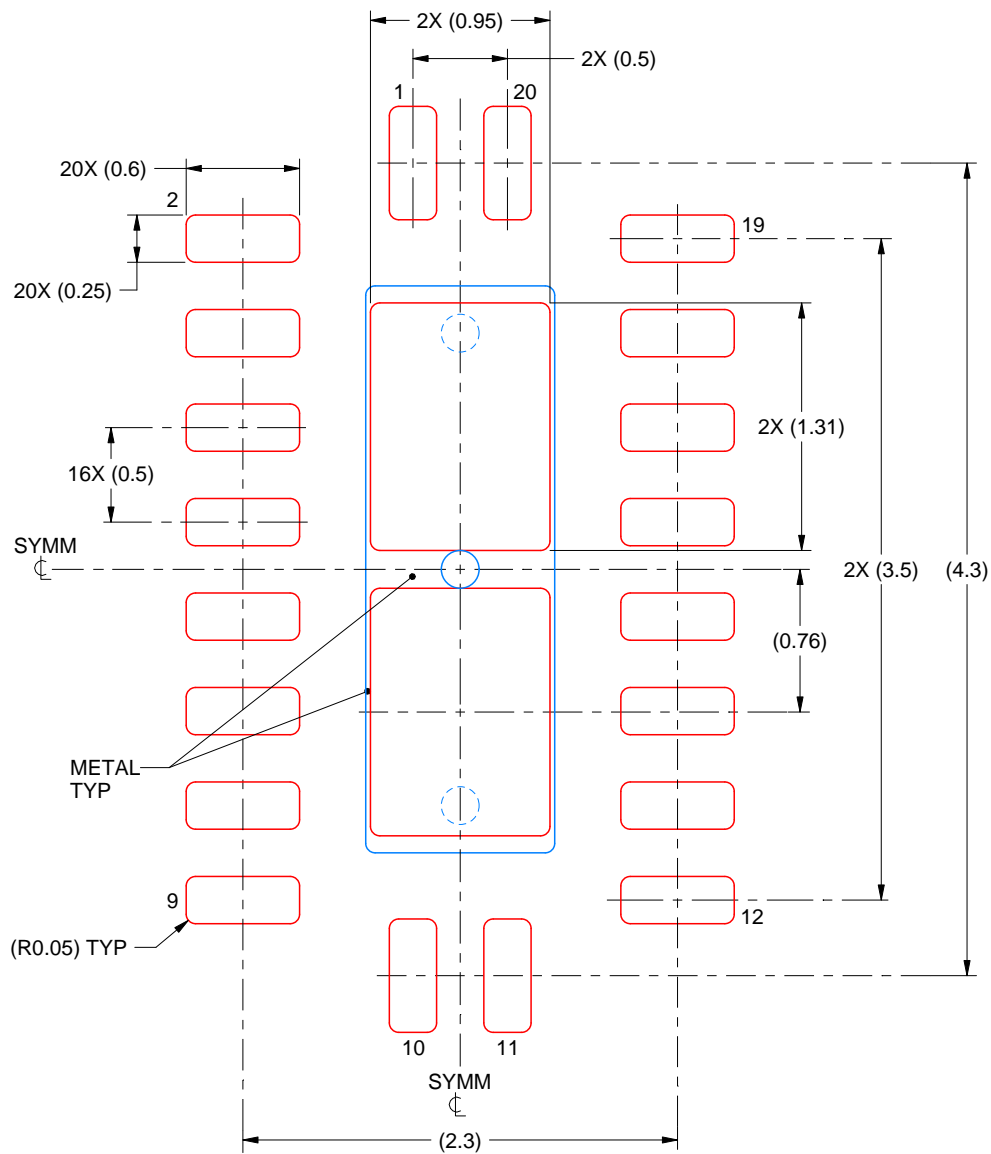
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
- Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown.

# EXAMPLE STENCIL DESIGN

RKS0020B

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE  
 BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD  
 83% PRINTED SOLDER COVERAGE BY AREA  
 SCALE:25X

4226762/B 06/2022

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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